

TOSHIBA

Toshiba will be at APEC 2024

Come check out what's on the horizon for power semiconductors



New technologies include:

- 650V Normally-On GaN
 - 35mΩ w/ integrated Pch Drive IC
- 650V/1200V SiC MOSFETs
 - 15 to 140mΩ w/ integrated SiC SBD

• Low Voltage Power MOSFETs

- New UMOS-11-H process
- Advanced Motor Control Solutions
 - BLDC Motor FOC control made easy



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Toshiba will be showcasing reference boards such as:

3-Phase Inverter Using SiC MOSFETs

- 3-phase AC 340 to 440 V, 15 A
- Link to reference design



ITTF 1.1kW AC-DC converter

• 1.1kW, Totem pole PFC+ITTF DC-DC

GaN Totem pole PFC for server power supply

• 2.5kW, 230Vin, 385Vout

HVAC ODU 3-in-1 reference using single MCU (RD219)

• 220AC to 330Vdc , PFC + ~10A compressor

inverter + 2A fan inverter

60kBTU ODU 3-in-1 reference using Single MCU

• 220AC to 330V, up to 25A Interleaved PFC,

16A compressor Inverter, 2A Fan inverter









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Toshiba will be also showcasing Ceramics and Magnetics

Examples of where Toshiba Ceramics have been used:

Power control unit (PCU)

 Electric control parts for HEV motors where TMAT SIN plane substrates are used.

Power module

Power modules where TMAT SiN AMC

substrates are used.

Ceramics and Magnetics:

SiN-Plane substrate

• Silicon Nitride ceramic substrates have great heat dissipation and strength

SiN-AMC substrate

• Insulated circuit board with a copper circuit formed by Active Metal Brazing

AMOBEADs

• Noise inhibiting devices with high magnetic permeability.









